



S T R A T E D G E

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Photo available at: <http://www.stratedge.com/stratedge-webinar.jpg>

## StratEdge On-demand Webinar about Packages and Eutectic Die Attach for GaN Devices is Now Available

*Explains how to reduce chip-to-package junction temperature to improve GaN chip efficiency and reliability*

Santee, Calif. — August 24, 2021 — StratEdge Corporation, leader in the design, production, and assembly of high-frequency and high-power semiconductor packages for microwave, millimeter-wave, and high-speed digital devices, announces that

the on-demand webinar, “Packages and Eutectic Die Attach for High-power GaN Devices,” is now available on the StratEdge website at [www.stratedge.com/webinar.html](http://www.stratedge.com/webinar.html). Learn how the package in which the gallium nitride (GaN) device is attached, and the method used to attach the device to the package, can optimize the device’s efficiency, performance, and reliability.

“By creating a package environment that reduces chip-to-package junction temperatures, GaN chip efficiency and reliability can be improved. The success of the package’s performance is dependent on the base material used, the quality of the package construction, and the attachment process,” explained Casey Krawiec, vice president of global sales at StratEdge. “Almost 20 years ago, StratEdge began developing package designs and [assembly processes](#) specifically for GaN chips that maximize thermal dissipation.”

The [webinar](#) “Packages and Eutectic Die Attach for High-power GaN Devices,” by Casey Krawiec, details how StratEdge’s post-fired ceramic package with a copper-molybdenum-copper (CMC) base, and its proprietary eutectic die attach method, results in a near void-free attachment



that reportedly reduces junction temperatures by 20 degrees Celsius as compared to standard assembly methods using ceramic packages of alternate construction.

The webinar is available on the StratEdge website at [www.stratedge.com/webinar.html](http://www.stratedge.com/webinar.html).

For more information, contact StratEdge at [info@stratedge.com](mailto:info@stratedge.com), or visit our website at [www.stratedge.com](http://www.stratedge.com).

### **About StratEdge**

[StratEdge Corporation](http://www.stratedge.com), founded in 1992, designs, manufactures, and provides assembly services for a complete line of high-frequency and high-power semiconductor packages operating from DC to 63+ GHz. StratEdge offers post-fired ceramic, low-cost molded ceramic, and ceramic QFN packages, and specializes in packages for extremely demanding gallium arsenide (GaAs) and gallium nitride (GaN) devices. Markets served include telecom for 5G, VSAT, broadband wireless, satellite, military, test and measurement, automotive, clean energy, and down-hole. All packages are lead-free and most meet RoHS and WEEE standards. StratEdge is ITAR registered and an ISO 9001:2015 certified facility located in Santee, California, near San Diego.

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